

## ABSTRACT

5 A process for manufacturing a composite polymeric circuit protection device in which a polymeric assembly is provided and is then subdivided into individual devices (2). The assembly is made by providing first and second laminates (7,8), each of which includes a laminar polymer element having at least one conductive surface, providing a pattern on at least one of the conductive surfaces on one laminate, securing the laminates in a stack (1) in a desired configuration, at least one conductive surface of at least one of 10 the laminates forming an external conductive surface (3) of the stack, and making a plurality of electrical connections (31,51) between a conductive surface of the first laminate and a conductive surface of the second laminate. The laminar polymer elements may be PTC conductive polymer compositions, so that the individual devices made by the process exhibit PTC behavior.

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